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By:

Date: Feb 26, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Robert-Christian Hagen et al.

Applic. No. : 09/993,266

Filed : November 19, 2001

Title : Electronic Component with Shielding and Method for its Production

P R E L I M I N A R Y A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Preliminary to examination, kindly amend the above-identified application as follows:

In the Claims:

Claim 13 (amended). A method for producing electronic components with shielding, which comprises the steps of:

A providing a semiconductor wafer functioning as a semiconductor substrate formed of a semiconductor material and having an